

# COPPER ON ALUMINUM NITRIDE

Thick film copper on aluminum nitride provides excellent electrical conductivity, leach resistance and solderability.

Typical Properties of Copper Metallization System	
<b>Resistivity</b>	2.0 mΩ/sq
<b>Printing Resolution</b> (line/space)	125 μm/125 μm
<b>Wettability</b> (5 sec dip, 62 Sn/36/2 Ag solder)	100%
<b>Adhesion*</b>	≥68.9 MPa

\*Pull testing with 3.0 mm square pads and epoxy adhesive aluminum studs.

Sienna's technical team is ready to help you implement Aluminum Nitride in your next generation of products.

**Contact us for applications assistance and fast prototyping.**

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